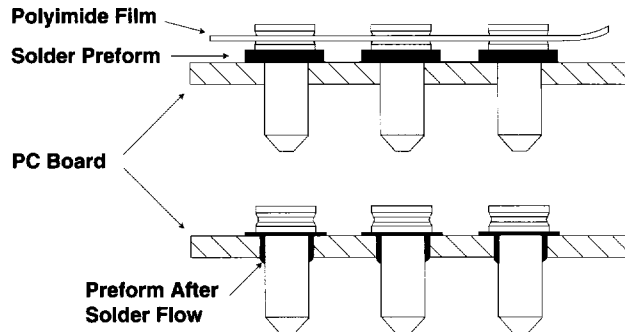
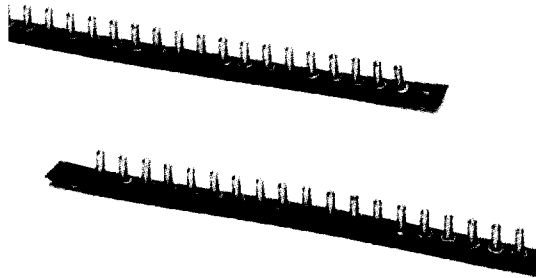


Solder Preform SIP Sockets



Features:

- Combines the labor of socket loading and solder application into one operation.
- Eliminates the use of solder paste and screening operation.
- Eliminates solder bridges and/or solder shorts due to excess solder.
- Insures a reliable solder joint with controlled solder volume.
- Ideal for surface mount and mixed technology applications.
- For custom solder preform terminal applications consult factory.
- Flux preforms available to customer requirements.
- See SIP pages 42 - 47 for additional material and dimensional information.

Terminals and Contacts:

Terminal: Brass - Copper Alloy 360, ASTM-B-16

Contact: Beryllium Copper - Copper Alloy 172, ASTM-B-194

Plating:

Terminal: Gold over Nickel or Tin-Lead over Nickel

Contact: Gold over Nickel or Tin-Lead over Nickel

Body Material:

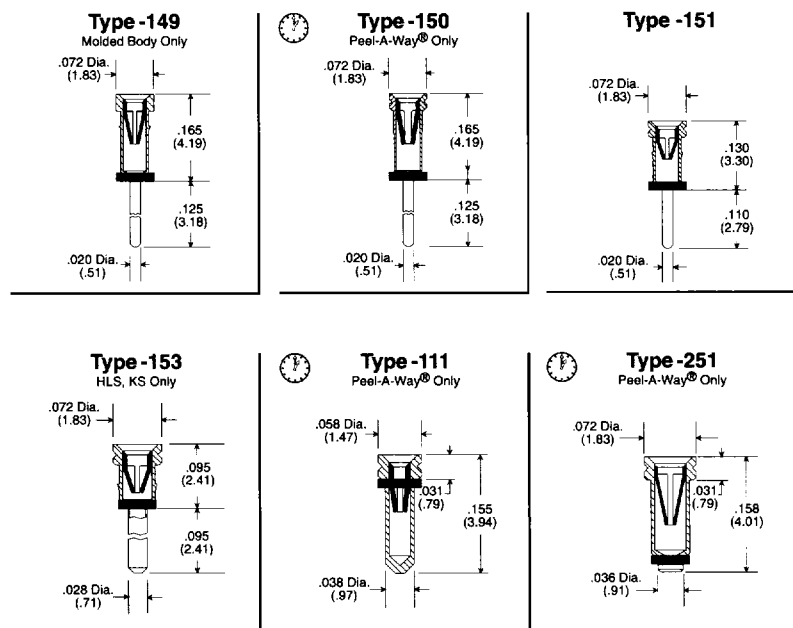
HSS/HLSS/HNB/HLNB - High Temp. Glass Filled Thermoplastic, U.L. Rated 94V-O, -60°C to 260°C (-76°F to 500°F)

KS - Polyimide Film -269°C to 400°C (-452°F to 752°F)

Solder Preform:

63% Tin, 37% Lead, RMA flux optional

Terminal Information



Quick turn delivery available on standard terminal types.

Additional terminal types available.

See terminal section for detailed terminal information.

How To Order

